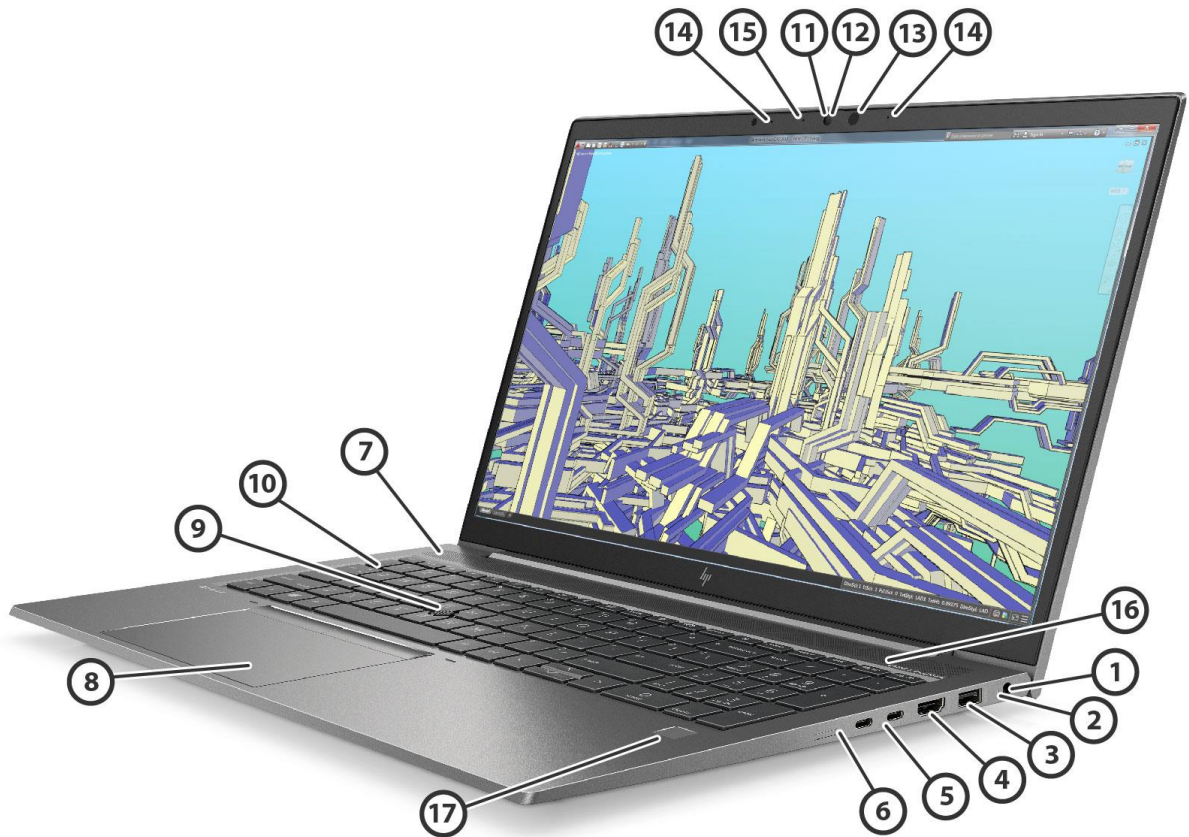


Overview

HP ZBook Firefly 15 G7 Mobile Workstation



Right

1. 4.5mm AC Power connector
2. Battery Charging LED
3. (1) USB 3.1 Gen 1 Type A
4. HDMI 2.0 (HDMI cable not included)
5. (2) USB Type-C® with Thunderbolt™ 3
6. Nano SIM card slot (optional)¹
7. Speakers
8. Clickpad
9. Dual point stick with buttons
10. HP Premium Keyboard
11. HD Camera (select models only)
12. IR Camera (select models only)
13. HP Privacy Camera Shutter
14. Multi-array microphone
15. Webcam LED
16. Power button (on keyboard)
17. fingerprint sensor (optional)

¹All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug

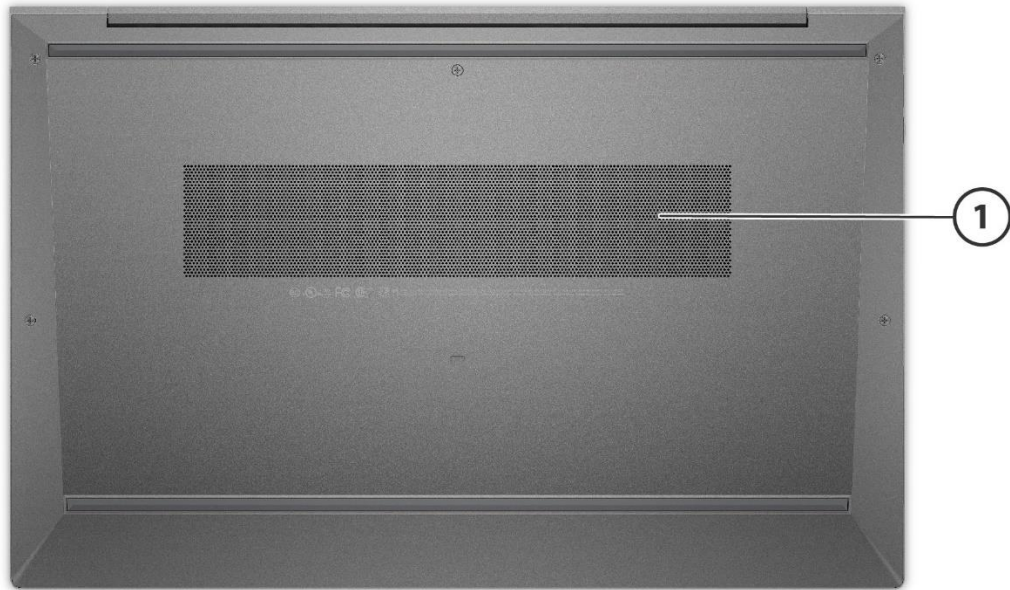
Overview



Left

1. Nano security lock slot (cable lock sold separately)
2. (1) USB 3.1 Gen 1 Type A charging port
3. Headphone/microphone combo jack
4. HP Smart Card Reader (optional)

Overview



Bottom

1. Fan Venting
-

Overview

At A Glance

- Work anywhere without compromising on performance or security with Windows 10 Pro¹, powered by HP's collaboration and connectivity technology.
- Open large files and run apps simultaneously for speedy multitasking and productivity with the NVIDIA® Quadro® P520 graphics with 4GB of video memory.
- Bring your ideas to life quickly and effectively with the 10th gen quad core Intel® Core™ processors² with up to 4.9 GHz of acceleration when you need it most.³
- Strenuously tested to meet ISV certification and deliver superb performance and support with leading software providers, including Autodesk and Adobe®.⁴
- Have confidence with the world's most secure mobile workstations.⁵ Instantly protect against visual hacking with HP Sure View Reflect⁶ and defend against firmware and malware attacks with HP Sure Start Gen6⁷ and HP Sure Sense⁸.
- Built with the environment in mind, this ZBook includes recycled ocean-bound plastics¹⁰, plastic-free packaging, a reduction in hazardous material and ultra-efficient power consumption.
- The keyboard has been re-imagined with rubber domes, power button, and a quiet clickpad for a more comfortable, intuitive, and quiet experience. Easily input numbers with a dedicate number pad.
- Choice of modern viewing experiences:
 - (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 400 nits, low power 100% sRGB
 - (39.6 cm) 15.6" diagonal, 4K UHD (3840 x 2160), IPS, anti-glare, 400 nits, 100% sRGB
 - (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 250 nits, 45% NTSC
 - (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 1000 nits, 72% NTSC, HP Sure View Reflect integrated
 - (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), touch, IPS, anti-glare, 250 nits, 45% NTSC
- Designed for ultimate durability, this ZBook undergoes brutal MIL-STD 810H ¹¹ tests to help ensure this PC keeps rolling through your workday.
- Plug in to greater connectivity at your desktop with the HP Thunderbolt Dock (120W) for lightning-fast Thunderbolt™ 3¹² transfers and the flexibility to run up to two external 4K displays.^{13,14}
- Work without limits in any location with up to 2TB¹⁵ of local PCIe storage.
- 170 degree clamshell hinges lay almost flat, for easy collaboration and comfortable viewing at every angle.
- No need to risk riding someone else's network when you have your own. Optional 4G LTE¹⁶ leverages the SIM card from your wireless provider for enhanced security.
- A completely revamped standby system means you're ready to work the moment inspiration strikes. With no sleep mode and no off mode, the modern standby keeps your rig connected and on demand whenever you need it.
- Improve connectivity while on Wi-Fi® with HP Extended Range Wireless LAN that allows greater distance from transmission point and fast data throughput at shorter ranges.¹⁷

¹Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

²Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

³Intel® Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

⁴Adobe and Autodesk software sold separately.

⁵Based on HP's unique and comprehensive security capabilities at no additional cost among desktop workstation vendors as of Sept. 2017 on HP Mobile Workstations with 7th Gen and higher Intel® Processors.

⁶HP Sure View Reflect integrated privacy screen is an optional feature that must be configured at purchase.

⁷HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.

⁸HP Sure Sense requires Windows 10. See product specifications for availability.

¹⁰Speaker enclosure component made with 5% ocean bound plastic as of 2/3/2020.

Overview

¹¹Testing is not intended to demonstrate fitness of U.S. Department of Defense (DoD) contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

¹²HP Thunderbolt Dock with Thunderbolt™ 3 sold separately.

¹³External displays sold separately.

¹⁴Optional hybrid graphics is required to run up to two external 4K displays.

¹⁵For hard drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30GB (for Windows 10) of system disk is reserved for system recovery software.

¹⁶4G LTE is an optional feature, requires separately purchased service contract, and configuration at purchase. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

¹⁷Based on internal testing vs. previous generation product with 802.11ac wireless LAN module.

NOTE: See important legal disclosures for all listed specs in their respective features sections.

Features

OPERATING SYSTEM

Preinstalled OS	Windows 10 Pro 64 - HP recommends Windows 10 Pro for business. ¹ Windows 10 Home 64 ¹ Windows 10 Home Single Language 64 ¹ Windows 10 Pro 64 ¹ FreeDOS 3.0
Web support OS	Windows 10 Enterprise 64 ¹
Supported Version	For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282 .

¹ Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See <http://www.windows.com>.

² Tested and documented only.

PROCESSOR

10th Generation Intel® Core™ i7-10810U vPro™ with Intel® UHD Graphics (1.1 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores)^{1,2,3,4}

10th Generation Intel® Core™ i7-10710U with Intel® UHD Graphics (1.1 GHz base frequency, up to 4.7 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 6 cores)^{1,2,3,4}

10th Generation Intel® Core™ i7-10510U with Intel® UHD Graphics (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{1,2,3,4}

10th Generation Intel® Core™ i7-10610U vPro™ with Intel® UHD Graphics (1.8 GHz base frequency, up to 4.9 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores)^{1,2,3,4}

10th Generation Intel® Core™ i5-10310U vPro™ with Intel® UHD Graphics (1.7 GHz base frequency, up to 4.4 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{1,2,3,4}

10th Generation Intel® Core™ i5-10210U vPro™ with Intel® UHD Graphics (1.6 GHz base frequency, up to 4.2 GHz with Intel® Turbo Boost Technology, 6 MB L3 cache, 4 cores)^{1,2,3,4}

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.

³ Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See www.intel.com/technology/turboboost for more information.

⁴ In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on <http://www.support.hp.com>.

Features

CHIPSET

Chipset is integrated with processor

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE

Intel® Core™ i5 with vPro™, Core™ i7 with vPro™, Core™ i9 with vPro™ is a selectable feature that is available on units configured with select processors, a qualified Intel® select WLAN module and a preinstalled Windows 10 Pro 64 and above. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel® Active Management Technology (iAMT)³ offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update regardless of their power state. ^{1,2}

¹ Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

² Some functionality of Intel® Core™ i5 with vPro™/Core™ i7 with vPro™ technology, such as Intel® Active Management technology and Intel® Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel® Core™ i5 with vPro™/Core i7 with vPro™ technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

³ Intel® Active Management Technology (iAMT) built-in manageability only available with Intel vPro processor + Intel vPro WLAN module

GRAPHICS

Integrated

Intel® UHD Graphics ^{1, 3, 5, 6}

Discrete

NVIDIA® Quadro® P520 (4 GB GDDR5 dedicated)^{2, 4}

¹ UHD content required to view UHD images.

² Both UMA & Discrete configurations support 3 independent displays when on the HP Thunderbolt Dock G2 (sold separately) - Max. resolution = 2.5K @60Hz (DP1) & 2.5K @60Hz (DP2) & FHD (VGA) OR 4K @60Hz (one DP Port) & 4K @60Hz (Type-C output port using a Type C-to-DP adapter).

³ Support HD decode, DX12, HDMI 2.0, HDCP 2.3 via DP up to 4K @ 60Hz and via HDMI up to 4K @ 30Hz

⁴ HDMI cable Sold Separately

⁵ Shared video memory (UMA) uses part of the total system memory for video performance. System memory dedicated to video performance is not available for other use by other programs.

DISPLAY

Non-touch

- (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 400 nits, low power 100% sRGB ^{3,4}
- (39.6 cm) 15.6" diagonal, 4K UHD (3840 x 2160), IPS, anti-glare, 400 nits, 100% sRGB^{2,3,4}
- (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 250 nits, 45% NTSC^{3,4}

Features

- (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 1000 nits, 72% NTSC, HP Sure View Reflect integrated privacy screen ^{1,3,4,5}

Touch

- (39.6 cm) 15.6" diagonal, FHD (1920 x 1080), touch, IPS, anti-glare, 250 nits, 45% NTSC^{3,4,5}

¹ HP Sure View Reflect is optional and must be configured at purchase.

² UHD content required to view UHD images.

³ Sold separately or as an optional feature.

⁴ Resolutions are dependent upon monitor capability, and resolution and color depth settings.

⁵ Actual brightness will be lower with HP Sure View or touch screen.

Features

STORAGE AND DRIVES*

PCIe® NVMe™ M.2 2280 Storage

256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Self Encrypting (SED) Solid State Drive (SSD)
512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Self Encrypting (SED) Solid State Drive (SSD)
256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD)
512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD)
1 TB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD)
2 TB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD)
256 GB PCIe® Gen3 x2 NVMe™ M.2 2280 TLC Value Solid State Drive (SSD)
128 GB PCIe® Gen3 x2 NVMe™ M.2 2280 TLC Solid State Drive (SSD)

Intel® Optane™ Memory H10 with Solid State Storage

512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 QLC Solid State Drive (SSD) + 32 GB Intel® Optane™ Memory¹

¹Intel® Optane™ memory system acceleration does not replace or increase the DRAM in your system.

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35GB of disk is reserved for system recovery software.

DRIVE CONTROLLERS

M.2 Storage Bay (PCIe NVMe)

PCIe Gen3 x4 lanes NVMe Solid State Drive

RAID:

Not supported

MEMORY

Maximum Memory

64 GB DDR4-2666 non-ECC SDRAM

2 DDR4 SODIMMS

Supports Dual Channel Memory¹

Slots are customer accessible / upgradeable

¹ Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

Features

NETWORKING/COMMUNICATIONS

WLAN

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, vPro™ ^{1,2}

Intel® Wi-Fi 6 AX201 (2x2) and Bluetooth® 5 combo, non-vPro™ ¹

¹Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for Wi-Fi 6 (802.11ax WLAN) are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax WLAN devices. Only available in countries where 802.11ax is supported.

²Intel® Active Management Technology (iAMT) built-in manageability only available with Intel vPro processor + Intel vPro WLAN module

WWAN^{1,2}

Intel® XMM™ 7360 LTE Advanced CAT 9

Intel® XMM™ 7560 LTE-Advanced Pro Cat 16

¹ WWAN is an optional feature and requires factory configuration and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

² Gigabit class Category 16 4G LTE module is optional and must be configured at the factory. Module designed for up to 1 Gbps download speeds as carriers deploy 5 carrier aggregation and 100Mhz channel bandwidth, requires activation and separately purchased service contract. Backwards compatible to HSPA 3G technologies. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 4G LTE not available on all products, in all regions.

Optional Near Field Communication (NFC) module

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen, dual stereo speakers, HP World Facing Microphone multi-array digital microphone, functions keys for volume up and down, combo microphone/headphone jack, HD audio.

Camera^{1, 2}

720p HD webcam with IR

720p HD webcam

¹ HD content required to view HD images.

² Windows Hello face authentication utilizes a camera specially configured for near infrared (IR) imaging to authenticate and unlock Windows devices as well as unlock your Microsoft Passport.

Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Premium Quiet Keyboard, full-size with NumPad, spill-resistant, backlit, with DuraKeys, clickpad with image sensor and glass surface, multi-touch gestures and taps enabled

HP Premium Quiet Keyboard, full-size with NumPad, spill-resistant, with DuraKeys, clickpad with image sensor and glass surface, multi-touch gestures and taps enabled

Pointing Devices

Dual pointstick; Clickpad with multi-touch gestures enabled, taps enabled as default;

Microsoft Precision Touchpad Default Gestures Support

SOFTWARE AND SECURITY

Software

Bing search for IE11

Buy Office

HP Hotkey Support

HP Noise Cancellation Software

HP Performance Advisor (download only)⁹

HP Recovery Manager

HP ZCentral Remote Boost Software (download only)²

HP Support Assistant¹

Native Miracast support⁵

HP Connection Optimizer¹⁰

HP PC Hardware Diagnostics UEFI

HP PC Hardware Diagnostics Windows

HP Privacy Settings

HP Touchpoint Customizer

myHP

HP Smart Support²⁰

Security Management

Absolute persistence module⁶

HP Device Access Manager

HP FingerPrint Sensor

HP Manageability Integration Kit Gen6¹¹

HP Power On Authentication

HP Support Assistant⁷

Nano Security lock slot¹²

Trusted Platform Module TPM 2.0 Embedded Security Chip

Master Boot Record security

Pre-boot authentication

Microsoft Defender¹⁰

HP Client Security Manager Gen5^{7, 17}

HP BIOSphere Gen6⁵

HP Sure Recover Gen3¹³

HP Sure Recover with Embedded Reimaging Gen3¹⁴

HP Sure Start Gen6^{5, 15}

HP Secure Erase¹⁶

HP Sure Sense¹⁸

BIOS Version

Features

ISO/IEC 19678: 2015 (formerly NIST 800-147) compliant
UEFI version: 2.7

For more information on HP Client Security Software Suite, refer to <http://www.hp.com/go/clientsecurity>.

¹ HP Support Assistant - Requires Windows and Internet Access.

² HP Z Central Remote Boost Software - The remote desktop solution for serious workstation users and their most demanding applications. Download at: <http://www.hp.com/go/RGS>.

³ HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to <http://www.hp.com/go/mobileconnect>.

⁴ Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: <http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast>.

⁵ HP BIOSphere Gen6 is available on select HP Pro, Elite and ZBook PCs. See product specifications for details. Features may vary depending on the platform and configurations. HP Sure Start Gen5 - Available on HP Elite and HP Z Workstation products equipped with Intel® 8th generation processors.

⁶ Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

<http://www.absolute.com/company/legal/agreements/computrace-agreement>. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

⁷ Requires Windows and Intel® 8th generation processors.

⁸ HP Performance Advisor Software - HP Performance Advisor is ready and waiting to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: <https://www8.hp.com/us/en/workstations/performance-advisor.html>

⁹ HP Connection Optimizer requires Windows 10.

¹⁰ Microsoft Defender Opt in and internet connection required for updates.

¹¹ HP Manageability Integration Kit can be downloaded from <http://www.hp.com/go/clientmanagement>.

¹² Security lock slot is Lock sold separately.

¹³ HP Sure Recover Gen3: See product specifications for availability. Requires an open, wired network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.

¹⁴ HP Sure Recover with Embedded Reimaging Gen3 is an optional feature which must be configured at purchase. See product specifications for availability. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before use to avoid loss of data.

¹⁵ HP Sure Start Gen6 is available on select HP PCs with Intel processors. See product specifications for availability.

¹⁶ For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.

¹⁷ HP Client Security Manager Gen6 requires Windows and is available on select HP Pro, Elite and ZBook PCs. See product specifications for details.

¹⁸ HP Sure Sense requires Windows 10. See product specifications for availability.

¹⁹ Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited.

²⁰ HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: <http://www.hp.com/smart-support>. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.

Features

POWER

Power Supply

Up to 23 hours¹

HP Long Life 3-cell, 56 Wh Li-ion polymer²

HP Smart 65 W External AC Power Adapter³

HP Smart 45 W External AC Power Adapter

Supports battery fast charge: approximately 50% in 30 minutes (defined under system hibernation and off mode)

¹ Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark <https://bapco.com/products/mobilemark-2014/> for additional details.

² Supports HP Fast Charge Technology

³45W Power Adapter is not available with Discrete Graphics Configurations.

ENVIRONMENTAL

Targeting ENERGY STAR® certified and EPEAT® GOLD registered configurations available ¹

Low halogen²

¹ Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. Status varies by country. Visit www.epeat.net for more information.

² External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

Features

WEIGHTS & DIMENSIONS

Dimensions (w x d x h)

35.95 x 23.36 x 1.92 cm

14.15 x 9.19 x 0.76 in

Weights

Starting at 1.7kg (3.74 lb)

Weight varies by configuration and components.

PORTS/SLOTS

Left side

1 headphone/microphone combo

1 SuperSpeed USB Type-A 5Gbps signaling rate (charging) [USB 3.1 Gen 1 Type A charging]

1 SIM Card Slot (optional)

Right side

1 4.5mm AC power connector

1 SuperSpeed USB Type-A 5Gbps signaling rate [USB 3.1 Gen 1 Type A]

1 HDMI 2.0b

2 Thunderbolt™ 3 (40Gbps signaling rate) with SuperSpeed USB Type-C® 10Gbps signaling rate

(USB Power Delivery, DisplayPort™ 1.2, HP Sleep and Charge) [USB Type-C® with Thunderbolt™ 3]

1 Nano SIM Card Slot (optional)

SERVICE AND SUPPORT

3-year limited warranty options available, depending on country. Batteries have a default one-year limited warranty except for Long Life Batteries which will have same 1-year or 3-year limited warranty as the platform. Optional¹ HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at <http://www.hp.com/go/cpc>.

¹Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.

Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5V		
	Average Operating Power(idle)	WIN10	System in idle mode + max panel brightness	Adapter Safety test condition
	Integrated graphics	6.78W	250nit, 400nits, 550nits	
	Discrete Graphics	15.3W		
	Max Operating Power	Discrete < 65W UMA < 45W		
Temperature	Operating	32° to 95° F (0° to 35° C) (not writing optical)		
	Non-operating	-4° to 140° F (-20° to 60° C) (writing optical)		
Relative Humidity	Operating	10% to 90%, non-condensing		
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature		
Shock	Operating	40 G, 2 ms, half-sine		
	Non-operating	200 G, 2 ms, half-sine		
Random Vibration	Operating	0.75 grms		
	Non-operating	1.50 grms		
Maximum Altitude (unpressurized)	Operating	-50 to 10,000 ft. (-15.24 to 3,048 m)		
	Non-operating	-50 to 15,000 ft. (-15.24 to 12,192 m)		
Planned Industry Standard Certifications	UL	Yes		
	CSA	Yes		
	FCC Compliance	Yes		
	ENERGY STAR®	Select models ¹		
	EPEAT®	Registered Gold in United States		
	ICES	Yes		
	Australia / NZ A-Tick Compliance	Yes		
	CCC	Yes		
	Japan VCCI Compliance	Yes		
	KCC	Yes		
	BSMI	Yes		
	CE Marking Compliance	Yes		
	MIL STD 810H	Yes, passed 19 tests		
	BNCI or BELUS	Yes		
	CIT	Yes		
	GOST	Yes		
	Saudi Arabian Compliance (ICCP)	Yes		
SABS	Yes			

¹Configurations of the HP ZBook Firefly 15 G7 that are ENERGY STAR® qualified are identified as HP ZBook Firefly 15 G7 ENERGY STAR on HP websites and on <http://www.energystar.gov>.

Technical Specifications – Displays

DISPLAYS

15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 250 nits, 45% NTSC	Outline Dimensions (W x H)	350.96 x 205.54 mm (max)		
	Active Area	344.16 x 193.59 mm (typ.)		
	Weight	370 g (max)		
	Diagonal Size	15.6 inch		
	Thickness	3.0 mm/ 5.0 mm (w/PCB) (max)		
	Interface	eDP 1.2 (2 lane)		
	Surface Treatment	Anti-Glare		
	Touch enabled	No		
	Contrast Ratio	600:1 (typ.)		
	Refresh Rate	60 Hz		
	Brightness	250 nits		
	Pixel Resolution	Pitch	1920 x 1080 (FHD)	
		Format	RGB Stripe	
	Backlight	LED		
	Color Gamut Coverage	NTSC 45%		
	Color Depth	6 bits (Hi FRC supportive w/ condition to enable)		
	Viewing Angle	UWVA 85/85/85/85		
	15.6" diagonal, FHD (1920 x 1080), touch, IPS, anti-glare, 250 nits, 45% NTSC	Outline Dimensions (W x H)	350.96 x 205.74 mm (max)	
		Active Area	344.16 x 193.59 mm (typ.)	
Weight		380 g (max)		
Diagonal Size		15.6 inch		
Thickness		3.2mm/ 5.2mm (PCB) (max)		
Interface		eDP 1.2		
Surface Treatment		Anti-Glare On-cell touch		
Touch enabled		YES		
Contrast Ratio		600:1 (typ.)		
Refresh Rate		60 Hz		
Brightness		250 nits		
Pixel Resolution		Pitch	1920 x 1080 (FHD)	
		Format	RGB Stripe	
Backlight		LED		
Color Gamut Coverage		NTSC 45%		
Color Depth		6 bits		
Viewing Angle		UWVA 85/85/85/85		

Technical Specifications – Displays

15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 400 nits, low power 100% sRGB	Outline Dimensions (W x H)	349.46 x 204.79 mm (max)		
	Active Area	344.16 x 193.59 mm (typ.)		
	Weight	325 g (max)		
	Diagonal Size	15.6 inch		
	Thickness	2.6mm / 4.6mm (PCB) (max)		
	Interface	eDP 1.4		
	Surface Treatment	Anti-Glare		
	Touch enabled	No		
	Contrast Ratio	1200:1 (typ.)		
	Refresh Rate	60 Hz		
	Brightness	400 nits		
	Pixel Resolution	Pitch	1920 x 1080 (FHD)	
		Format	RGB Stripe	
	Backlight	LED		
	Color Gamut Coverage	sRGB 100% (NTSC 72%)		
	Color Depth	8 bit		
	Viewing Angle	UWVA 85/85/85/85		
	15.6" diagonal, 4K UHD (3840 x 2160), IPS, anti-glare, 400 nits, low power 100% sRGB	Outline Dimensions (W x H)	349.52 x 205.42 mm (max)	
		Active Area	344.22 x 193.62 mm (typ.)	
Weight		320 g (max)		
Diagonal Size		15.6 inch		
Thickness		2.6mm / 4.6mm (PCB) (max)		
Interface		eDP 1.4		
Surface Treatment		Anti-Glare		
Touch Enabled		No		
Contrast Ratio		1200:1 (typ.)		
Refresh Rate		60 Hz		
Brightness		400 nits		
Pixel Resolution		Pitch	3840 x 2160 (UHD)	
		Format	RGB Stripe	
Backlight		LED		
Color Gamut Coverage		sRGB 100% only for UHD LP		
Color Depth		8 bit		
Viewing Angle		UWVA 85/85/85/85		
		Outline Dimensions (W x H)	349.52 x 205.39 mm (max)	

Technical Specifications – Displays

15.6" diagonal, FHD (1920 x 1080), IPS, anti-glare, 1000 nits, 72% NTSC, HP Sure View Reflect integrated privacy screen	Active Area	344.16 x 193.59 mm (typ.)		
	Weight	370 g (max)		
	Diagonal Size	15.6 inch		
	Thickness	2.6mm / 4.6mm (PCB) (max)		
	Interface	eDP 1.4 + PSR		
	Surface Treatment	Anti-Glare (AG)		
	Touch Enabled	No		
	Contrast Ratio	1500:1 (typ)		
	Refresh Rate	60 Hz		
	Brightness	1000 nits		
	Pixel Resolution	Pitch	1920 x 1080 (FHD)	
		Format	RGB	
	Backlight	LED		
	PPI	141		
Color Gamut Coverage	100% sRGB			
Color Depth	8 bit			
Viewing Angle	UWVA 85/85/85/85			

Options and Accessories

	Part #
HP USB-C Dock G5	5TW10AA
HP USB-C/A Universal Dock G2	5TW13AA
HP TB Dock G2 w/ Combo Cable	3TR87AA

Technical Specifications – Storage

STORAGE AND DRIVES

256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD)

Form Factor	M.2 2280	
Drive Weight	0.02 lb (10 g)	
Capacity	256 GB	
NAND Type	TLC	
Height	0.09 in (2.3 mm)	
Width	0.87 in (22 mm)	
Interface	PCIe® Gen3 x4 NVMe™	
Performance	Maximum Sequential Read	Maximum Sequential Write
	2800 ~ 3500 MB/s	1400 ~ 2200 MB/s
Logical Blocks	500,118,192	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security; TRIM; L1.2	

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

256 GB PCIe® Gen3 x2 NVMe™ M.2 2280 TLC Value Solid State Drive (SSD)

Form Factor	M.2 2280	
Drive Weight	0.02 lb (10 g)	
Capacity	256 GB	
NAND Type	Value TLC	
Height	0.09 in (2.3 mm)	
Width	0.87 in (22 mm)	
Interface	PCIe® Gen3 x2 NVMe™	
Performance	Maximum Sequential Read	Maximum Sequential Write
	2100 ~ 2200 MB/s	900 ~ 1400 MB/s
Logical Blocks	500,118,192	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security (optional); TRIM; L1.2	

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 QLC Solid State Drive (SSD) + 16 GB Intel® Optane™ Memory

Form Factor	M.2 2280	
Drive Weight	0.02 lb (10 g)	
Capacity	256 GB + 16 GB	
Generation	H10	
NAND Type	QLC + 3D XPoint	
Height	0.09 in (2.3 mm)	
Width	0.87 in (22 mm)	
Interface	PCIe® Gen3 x4 NVMe™	
Performance	Maximum Sequential Read	Maximum Sequential Write
	Up to 1450 MB/s	Up to 500 MB/s
Logical Blocks	500,118,192	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	

Technical Specifications – Storage

	Features	ATA Security; TRIM; L1.2		
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.		
256 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Self Encrypting (SED) Solid State Drive (SSD)	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	256 GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe® Gen3 x4 NVMe™		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		2800 ~ 3500 MB/s	1663 ~ 2200 MB/s	
	Logical Blocks	500,118,192		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2		
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.		
512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD)	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	512 GB		
	NAND Type	TLC		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe® Gen3 x4 NVMe™		
	Performance	Maximum Sequential Read	Maximum Sequential Write	
		3100 ~ 3500 MB/s	2400 ~ 2956 MB/s	
	Logical Blocks	1,000,215,215		
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]		
	Features	ATA Security; TRIM; L1.2		
		Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.		
512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 QLC Solid State Drive (SSD) + 32 GB Intel® Optane™ Memory	Form Factor	M.2 2280		
	Drive Weight	0.02 lb (10 g)		
	Capacity	512 GB + 32 GB		
	Generation	H10		
	NAND Type	QLC + 3D XPoint		
	Height	0.09 in (2.3 mm)		
	Width	0.87 in (22 mm)		
	Interface	PCIe® Gen3 x4 NVMe™		
	Performance	Maximum Sequential Read	Maximum Sequential Write	

Technical Specifications – Storage

Up to 2400 MB/s Up to 1300 MB/s

Logical Blocks	1,000,215,215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

512 GB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Self Encrypting (SED) Solid State Drive (SSD)

Form Factor	M.2 2280
Drive Weight	0.02 lb (10 g)
Capacity	512 GB
NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Interface	PCIe® Gen3 x4 NVMe™
Performance	Maximum Sequential Read Maximum Sequential Write
	3100 ~ 3500 MB/s 2400 ~ 2956 MB/s

Logical Blocks	1,000,215,215
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

1 TB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD)

Form Factor	M.2 2280
Drive Weight	0.02 lb (10 g)
Capacity	1 TB
NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)
Interface	PCIe® Gen3 x4 NVMe™
Performance	Maximum Sequential Read Maximum Sequential Write
	3100 ~ 3500 MB/s 2770 ~ 3037 MB/s

Logical Blocks	2,000,409,264
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]
Features	ATA Security; TRIM; L1.2

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

2 TB PCIe® Gen3 x4 NVMe™ M.2 2280 TLC Solid State Drive (SSD)

Form Factor	M.2 2280
Drive Weight	0.02 lb (10 g)
Capacity	2TB
NAND Type	TLC
Height	0.09 in (2.3 mm)
Width	0.87 in (22 mm)

Technical Specifications – Storage

Interface	PCIe® Gen3 x4 NVMe™	
Performance	Maximum Sequential Read	Maximum Sequential Write
	3180 ~ 3500 MB/s	2920 ~ 3000 MB/s
Logical Blocks	3,907,029,168	
Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
Features	ATA Security (Option); TRIM; L1.2	

Note: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 35 GB (for Windows 10) is reserved for system recovery software.

Technical Specifications – Networking

NETWORKING/COMMUNICATION

Intel Wi-Fi 6 AX201 + BT5 Wireless LAN Standards (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) non-vPro

IEEE 802.11a
 IEEE 802.11b
 IEEE 802.11g
 IEEE 802.11n
 IEEE 802.11ac
 IEEE 802.11ax
 IEEE 802.11d
 IEEE 802.11e
 IEEE 802.11h
 IEEE 802.11i
 IEEE 802.11k
 IEEE 802.11r
 IEEE 802.11v

Interoperability

Wi-Fi certified

Frequency Band

802.11b/g/n/ax
 • 2.402 – 2.482 GHz
 802.11a/n/ac/ax
 • 4.9 – 4.95 GHz (Japan)
 • 5.15 – 5.25 GHz
 • 5.25 – 5.35 GHz
 • 5.47 – 5.725 GHz
 • 5.825 – 5.850 GHz

Data Rates

• 802.11b: 1, 2, 5.5, 11 Mbps
 • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
 • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
 • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
 • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
 • 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)

Modulation

Direct Sequence Spread Spectrum
 OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security¹

• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only
 • AES-CCMP: 128 bit in hardware
 • 802.1x authentication
 • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
 • WPA2 certification
 • WPA3 certification
 • IEEE 802.11i
 • WAPI

Network Architecture Models

Ad-hoc (Peer to Peer)
 Infrastructure (Access Point Required)

Roaming

IEEE 802.11 compliant roaming between access points

Output Power²

• 802.11b : +18.5dBm minimum
 • 802.11g : +17.5dBm minimum

Technical Specifications – Networking

	<ul style="list-style-type: none"> • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode 2.0 W • Receive mode 1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode 50 mW (WLAN unassociated) • Connected Standby 10mW • Radio disabled 8 mW
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode
Receiver Sensitivity³	<ul style="list-style-type: none"> •802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm
Weight	1. Type 2230 : 2.8g 2. Type 126: 1.3g
Operating Voltage	3.3v +/- 9%
Temperature	Operating 14° to 158° F (-10° to 70° C) Non-operating -40° to 176° F (-40° to 80° C)
Humidity	Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing)
Altitude	Operating Non-operating 0 to 10,000 ft (3,048 m) 0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio Off; LED Off – Radio ON
HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology	
Frequency Band	2402 to 2480 MHz

Technical Specifications – Networking

Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management Certifications	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)

Intel Wi-Fi 6 AX201 + BT5 Wireless LAN Standards (802.11ax 2x2, vPro, supporting gigabit file transfer speeds) vPro

IEEE 802.11a
IEEE 802.11b
IEEE 802.11g
IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ax
IEEE 802.11d
IEEE 802.11e
IEEE 802.11h

Technical Specifications – Networking

	IEEE 802.11i IEEE 802.11k IEEE 802.11r IEEE 802.11v
Interoperability	Wi-Fi certified
Frequency Band	802.11b/g/n/ax <ul style="list-style-type: none"> • 2.402 – 2.482 GHz 802.11a/n/ac/ax <ul style="list-style-type: none"> • 4.9 – 4.95 GHz (Japan) • 5.15 – 5.25 GHz • 5.25 – 5.35 GHz • 5.47 – 5.725 GHz • 5.825 – 5.850 GHz
Data Rates	<ul style="list-style-type: none"> • 802.11b: 1, 2, 5.5, 11 Mbps • 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps • 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) • 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) • 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)
Modulation	Direct Sequence Spread Spectrum OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
Security¹	<ul style="list-style-type: none"> • IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only • AES-CCMP: 128 bit in hardware • 802.1x authentication • WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. • WPA2 certification • WPA3 certification • IEEE 802.11i • WAPI
Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
Roaming	IEEE 802.11 compliant roaming between access points
Output Power²	<ul style="list-style-type: none"> • 802.11b : +18.5dBm minimum • 802.11g : +17.5dBm minimum • 802.11a : +18.5dBm minimum • 802.11n HT20(2.4GHz) : +15.5dBm minimum • 802.11n HT40(2.4GHz) : +14.5dBm minimum • 802.11n HT20(5GHz) : +15.5dBm minimum • 802.11n HT40(5GHz) : +14.5dBm minimum • 802.11ac VHT80(5GHz) : +11.5dBm minimum • 802.11ac VHT160(5GHz) : +11.5dBm minimum • 802.11ax HT40(2.4GHz) : +10dBm minimum • 802.11ax VHT160(5GHz) : +10dBm minimum
Power Consumption	<ul style="list-style-type: none"> • Transmit mode :2.0 W • Receive mode :1.6 W • Idle mode (PSP) 180 mW (WLAN Associated) • Idle mode :50 mW (WLAN unassociated)

Technical Specifications – Networking

	<ul style="list-style-type: none"> • Connected Standby/Modern Standby: 10mW • Radio disabled: 8 mW 				
Power Management	ACPI and PCI Express compliant power management 802.11 compliant power saving mode				
Receiver Sensitivity³	<ul style="list-style-type: none"> •802.11b, 1Mbps : -93.5dBm maximum •802.11b, 11Mbps : -84dBm maximum • 802.11a/g, 6Mbps : -86dBm maximum • 802.11a/g, 54Mbps : -72dBm maximum • 802.11n, MCS07 : -67dBm maximum • 802.11n, MCS15 : -64dBm maximum • 802.11ac, MCS0 : -84dBm maximum • 802.11ac, MCS9 : -59dBm maximum •802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum 				
Antenna Type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications				
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface				
Dimensions	<ol style="list-style-type: none"> 1. Type 2230 : 2.3 x 22.0 x 30.0 mm 2. Type 1216: 1.67 x 12.0 x 16.0 mm 				
Weight	<ol style="list-style-type: none"> 1. Type 2230 : 2.8g 2. Type 126: 1.3g 				
Operating Voltage	3.3v +/- 9%				
Temperature	<table border="0"> <tr> <td>Operating</td> <td>14° to 158° F (-10° to 70° C)</td> </tr> <tr> <td>Non-operating</td> <td>-40° to 176° F (-40° to 80° C)</td> </tr> </table>	Operating	14° to 158° F (-10° to 70° C)	Non-operating	-40° to 176° F (-40° to 80° C)
Operating	14° to 158° F (-10° to 70° C)				
Non-operating	-40° to 176° F (-40° to 80° C)				
Humidity	<table border="0"> <tr> <td>Operating</td> <td>10% to 90% (non-condensing)</td> </tr> <tr> <td>Non-operating</td> <td>5% to 95% (non-condensing)</td> </tr> </table>	Operating	10% to 90% (non-condensing)	Non-operating	5% to 95% (non-condensing)
Operating	10% to 90% (non-condensing)				
Non-operating	5% to 95% (non-condensing)				
Altitude	<table border="0"> <tr> <td>Operating</td> <td>0 to 10,000 ft (3,048 m)</td> </tr> <tr> <td>Non-operating</td> <td>0 to 50,000 ft (15,240 m)</td> </tr> </table>	Operating	0 to 10,000 ft (3,048 m)	Non-operating	0 to 50,000 ft (15,240 m)
Operating	0 to 10,000 ft (3,048 m)				
Non-operating	0 to 50,000 ft (15,240 m)				
LED Activity	LED Amber – Radio OFF; LED White – Radio ON				
HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology					
Frequency Band	2402 to 2480 MHz				
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)				
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps BLE : 1 Mbps data rate; throughput up to 0.2 Mbps Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)				
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.				

Technical Specifications – Networking

Power Consumption	Peak (Tx): 330 mW Peak (Rx): 230 mW Selective Suspend: 17 mW
Bluetooth Software Supported	Microsoft Windows Bluetooth Software
Link Topology	
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power Management	ETS 300 328, ETS 300 826
Certifications	Low Voltage Directive IEC950 UL, CSA, and CE Mark
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® XMM™ 7360 LTE-Advanced CAT9*

Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
GPS	Standalone, A-GPS (MS-A, MS-B)
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
Maximum data rates	LTE: 450 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Technical Specifications – Networking

Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	5.8 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Intel® XMM™ 7560 LTE-Advanced Pro DL CAT16*

Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 14 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1900 (Band 25), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 1700/2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41), 3500 (Band 42), 5200 (Band 46 RX only) HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 12 LTE Specification DL-CAT.16, DL 100MHz BW throughput up to 978Mbps; UL-CAT.7 20MHz throughput up to 75Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
GPS	Standalone, A-GPS (MS-A, MS-B)
GPS Bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou 1561.098 MHz
Maximum Data Rates	LTE: 978 Mbps (Download), 75 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)
Maximum Output Power	LTE: 23 dBm in all band except B41 LTE B41 HPUE = 26dBm HSPA+: 23.5 dBm
Maximum Power Consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

* Mobile Broadband is an optional feature and requires configuration at purchase. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Technical Specifications – Networking

Near Field Communications Controller (optional)

Dimensions (L x W x H)	Module 25 mm by 10 mm by 2.0 mm		
Chipset	NPC100		
System interface	I2C		
NFC RF standards	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-320 NFCIP-2		
NFC Forum Support	Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2		
Reader (PCD-VCD) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards		
Card Emulation (PICC-VICC) Mode(1)	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa		
Frequency	13.56 MHz		
NFC Modes Supported	Reader/Writer, Peer-to-Peer		
Raw RF Data Rates	106, 212, 424, 848 kbps		
Operating temperature	0°C to 70°C		
Storage temperature	-20°C to 125°C		
Humidity	10-90% operating 5-95% non-operating		
Supply Operating voltage	4.35 to 5.25 Volts		
I/O Voltage	1.8V or 3.3V		
Power Consumption	Booster enable, VCC_BOOST = 5V) Mode Power Consumption, Typical	VBAT= 3.3V, Polling	Detected Test
			Tag Type 1
			Detected Test
			Tag Type 2
			Detected Test
			Tag Type 3
			Detected Test
			Tag Type 4
Antenna	Antenna connector, 0.5mm pitch, 7 connector FPC. Antenna matching is external to module.		

Technical Specifications – Power

POWER

HP 45W Smart AC Adapter (nPFC Standard Barrel 4.5mm Right Angle 1.8m)	Dimensions	95x45x26.8mm	
	Weight	unit: 200g +/- 10g	
	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47 ~ 63 Hz
	Output	Input AC current	Max. 1.4 A at 90 Vac
		Output power	45W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
		Connector	4.5mm Barrel Type
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
Storage Humidity		10% to 95%	
EMI and Safety Certifications	Eg: *CE Mark - full compliance with LVD and EMC directives * Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. * MTBF - over 200,000 hours at 25°C ambient condition.		

HP 45W Smart AC Adapter (nPFC Standard Barrel 4.5mm Right Angle 1.8m 2prong)	Dimensions	95x45x26.8mm	
	Weight	unit: 200g +/- 10g	
	Input	Input Efficiency	87.74 % at 115 Vac and 88.4 % at 230Vac
		Input frequency range	47 to 63 Hz
	Output	Input AC current	Max. 1.4 A at 90 Vac
		Output power	45W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<8.0A
		Connector	4.5mm Barrel Type
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)

Technical Specifications – Power

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 20% to 95%

Storage Humidity 10% to 95%

EMI and Safety Certifications

Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC Adapter (nPFC Slim USB-C® Straight 1.8m)

Dimensions

88x53.5x21mm

Weight

unit: 220g +/- 10g

Input

Input Efficiency

81.5% min at 115 Vac/ 230Vac @ 5V/3A
 86.7% min at 115 Vac/ 230Vac @ 9V/3A
 88% min at 115 Vac/ 230Vac @ 12V/5A
 89% min at 115 Vac/ 230Vac @ 15V/4.33A
 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range

47 ~ 63 Hz

Input AC current

1.6 A at 90 VAC and maximum load

Output

Output power

65W

DC output

5V/9V/12V/15V/20V

Hold-up time

5ms at 115 Vac input

Output current limit

<8.0A

Connector

USB Type C®

Environmental Design

Operating temperature

32° to 95° F (0° to 35° C)

Non-operating (storage) temperature

-4° to 185° F (-20° to 85° C)

Altitude

0 to 16,400 ft (0 to 5000m)

Humidity

5% to 95%

Storage Humidity

5% to 95%

EMI and Safety Certifications

Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 100,000 hours at 25°C ambient condition.

Technical Specifications – Power

HP 65W Smart AC Adapter (nPFC Standard USB-C® Straight 1.8m)	Dimensions	90.0x51x28.5mm	
	Weight	unit: 250g +/- 10g	
	Input	Input Efficiency	81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A
		Input frequency range	47 ~ 63 Hz
	Output	Input AC current	1.6 A at 90 VAC and maximum load
		Output power	65W
		DC output	5V/9V/12V/15V/20V
		Hold-up time	5ms at 115 Vac input
		Output current limit	8.0A Max.
	Connector	USB TYPE C®	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
EMI and Safety Certifications	Eg: "CE Mark - full compliance with LVD and EMC directives *Worldwide safety standards -IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. *MTBF - over 200,000 hours at 25°C ambient condition.		
HP 65W Smart AC Adapter (nPFC Standard Barrel 4.5mm for Emerging Markets)	Dimensions	102x55x30mm	
	Weight	unit: 250g +/- 10g	
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
		Input frequency range	47 ~ 63 Hz
	Output	Input AC current	Max. 1.7 A at 90 Vac
		Output power	65W
		DC output	19.5V
		Hold-up time	5ms at 115 Vac input
		Output current limit	<11.0A
	Connector	4.5mm Barrel Type	
	Environmental Design	Operating temperature	32oF to 95oF (0oto 35oC)
		Non-operating (storage) temperature	-4oF to 185oF (-20oto 85oC)
		Altitude	0 to 16,400 ft (0 to 5,000 m)

Technical Specifications – Power

Humidity 20% to 95%

Storage Humidity 10% to 95%

EMI and Safety Certifications

Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 65W Smart AC Adapter (nPFC Standard Barrel 4.5mm Right Angle 1.8m)

Dimensions

90x51x28.5mm

Weight

unit: 230g +/- 10g

Input

Input Efficiency

88.0 % at 115 Vac and 89.0 % at 230Vac

Input frequency range

47 ~ 63 Hz

Input AC current

Max. 1.7 A at 90 Vac

Output

Output power

65W

DC output

19.5V

Hold-up time

5ms at 115 Vac input

Output current limit

<11.0A

Connector

4.5mm Barrel Type

Environmental Design

Operating temperature

32° to 95° F (0° to 35° C)

Non-operating (storage) temperature

-4° to 185° F (-20° to 85° C)

Altitude

0 to 16,400 ft (0 to 5,000 m)

Humidity

20% to 95%

Storage Humidity

10% to 95%

EMI and Safety Certifications

Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 200,000 hours at 25°C ambient condition.

HP 3-cell Long Life Battery (56 WHr) supporting HP Fast Charge

Dimensions (H x W x L)

7.0 x 66.5 x 276.3 mm (0.275 x 2.618 x 10.877 inch)

Weight

0.215kg (0.45 lb)

Cells/Type

3cell Lithium-Ion Polymer cell / 615383

Energy

Voltage

11.55V

Amp-hour capacity

4.59Ah

Watt-hour capacity

56Wh

Temperature

Operating (Charging)

32° to 122° F (0° to 50° C)

Operating (Discharging)

14° to 140° F (-10° to 60° C)

Fuel Gauge LED

NA

Technical Specifications – Power

Warranty	Depends on system offering
Optional Travel Battery Available	No

Technical Specifications – Environmental

ENVIRONMENTAL DATA

Eco-Label Certifications & declarations

This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- US ENERGY STAR®
- EPEAT® Gold registered in the United States. See <http://www.epeat.net> for registration status in your country.

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a “Typically Configured Notebook”.

Energy Consumption (in accordance with US ENERGY STAR® test method)

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	5.70 W	5.74 W	5.49 W
Normal Operation (Long idle)	2.99 W	2.43 W	2.31 W
Sleep	1.37 W	1.38 W	1.32 W
Off	0.35 W	0.52 W	0.35 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family. HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*

	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	12 BTU/hr	12 BTU/hr	12 BTU/hr
Normal Operation (Long idle)	6 BTU/hr	5 BTU/hr	5 BTU/hr
Sleep	3 BTU/hr	3 BTU/hr	3 BTU/hr
Off	1 BTU/hr	1 BTU/hr	1 BTU/hr

***NOTE:** Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)

	Sound Power (L _{WAd} , bels)	Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.5	14
Fixed Disk – Random writes	2.8	20

Longevity and Upgrading

"This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include:

- 3 USB ports
- 2 SODIMM memory slots
- Interchangeable HDD

Technical Specifications – Environmental

Spare parts are available throughout the warranty period and or for up to “5” years after the end of production.

Batteries

This battery(s) in this product comply with EU Directive 2006/66/EC

Batteries used in the product do not contain:

- Mercury greater than 1ppm by weight
- Cadmium greater than 20ppm by weight

Battery description: CR2032 (coin cell)

Battery type: Lithium

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product contains 7.8% post-consumer recycled plastic (by wt.)
- This product is 96.1% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Cardboard & misc	235 g
Internal:	PLASTIC/EPE (Expanded Polyethylene)	27 g
	PLASTIC/Polyethylene low density	13 g
	PLASTIC/Polypropylene	3 g

The plastic packaging material contains at least 50% recycled content.

The corrugated paper packaging materials contains at least 70% recycled content.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf>):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances

Technical Specifications – Environmental

- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) – except for wires and cables, has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: <http://www.hp.com/go/reuse-recycle> or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the HP web site at: <http://www.hp.com/go/recyclers>. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.

HP Inc. Corporate Environmental Information

For more information about HP's commitment to the environment:

Global Citizenship Report

<http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html>

Eco-label certifications

<http://www8.hp.com/us/en/hp-information/environment/ecolabels.html>

ISO 14001 certificates:

<http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842>

and

<http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf>

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Date of change:	Version History:		Description of change:
July 22, 2020	From v1 to v2	Changed	OPERATING SYSTEM, PROCESSOR, WEIGHTS & DIMENSIONS and ENVIRONMENTAL DATA sections
November 11, 2020	From v2 to v3	Changed	At A Glance, OPERATING SYSTEM, GRAPHICS, DISPLAY, STORAGE AND DRIVES, KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS, SOFTWARE AND SECURITY, PORTS/SLOTS sections
December 16, 2020	From v3 to v4	Added	BIOS Version in Software and Security section
February 3, 2021	From v4 to v5	Added	Options and Accessories section
February 8, 2021	From v5 to v6	Changed	NETWORKING/COMMUNICATION section
April 22, 2021	From v6 to v7	Changed	INTEL CORE I5 WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE and NETWORKING/COMMUNICATIONS sections
May 31, 2021	From v7 to v8	Added	HP Smart Support and footnote
June 10, 2021	From v8 to v9	Removed	Workwell from Software section
June 16, 2021	From v9 to v10	Changed	SYSTEM UNIT Temperature section
September 3, 2021	From v10 to v11	Changed	GRAPHICS section